

# DATA SHEET

## B1S~B10S

## MINI SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

### VOLTAGE - 100 to 1000 Volts CURRENT - 0.5 Amperes

### FEATURES

· Plastic material used carries Underwriters

- Laboratory recognition 94V-O
- Low leakage
- Surge overload rating-- 30 amperes peak
- · Ideal for printed circuit board
- Exceeds environmental standards of MIL-S-19500

#### **MECHANICALDATA**

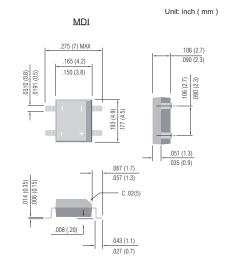
Case: Reliable low cost construction utilizing molded plastic technique results in inexpensive product

Terminals: Lead solderable per MIL-STD-202, Method 208.

Polarity: Polarity symbols molded or marking on body.

Mounting Position: Any.

Weight: 0.008 ounce, 0.22 gram.



#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, Resistive or inductive load. For capacitive load, derate current by 20%

	B1S	B2S	B4S	B6S	B8S	B10S	UNIT
Maximum Recurrent Peak Reverse Voltage	100	200	400	600	800	1000	V
Maximum RMS Bridge input Voltage	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	100	200	400	600	800	1000	V
$\begin{array}{llllllllllllllllllllllllllllllllllll$	0.5 0.8						А
Peak Forward Surge Current, 8.3ms singlehalf sine-wave superimposed on rated load	30.0						А
$I^{2}t$ Rating for fusing ( t < 8.35 ms)	5.0						A <sup>2</sup> t
Maximum Forward Voltage Drop per Bridge Element at 0.5A	1.00						v
Maximum Reverse Current at Rated T <sub>J</sub> = 25°C DC Blocking Voltage per element T <sub>J</sub> =125°C	5.0						μA mA
Typical Junction capacitance per leg (Note 1) CJ	25.0						pF
Typical Thermal resistance per leg (Note 2) RθJA Typical Thermal resistance per leg (Note 2) RθJA	85.0						°C/W
Operating Temperature Range T <sub>J</sub>	-55 to 150						°C
Storage Temperature Range T <sub>A</sub>	-55 to 150						°C

NOTES:

1. Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts

2. Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.05 X 0.05" (13 x 13mm) copper pads.

3. On alum: substrate P.C.B with an rea of 0.8 x 0.8 x 0.25" ( 20 x 20 x 6.4mm ) mounte on 0.05 x 0.05 "( 13 x 13 mm ) solder pad.



